

Prohibited & Restricted Substances

We began prohibiting and restricting the intentional use of certain hazardous substances in our semiconductor business's integrated-circuit product design in 2003.

Today our list of prohibited or restricted substances for those products includes:

- Antimony
- Asbestos
- Azo compounds
- Brominated flame retardant and chlorinated flame retardant
- Bromine
- Cadmium and cadmium compounds
- Chlorinated paraffins (CP)
- Chlorine
- 4,4'-Diaminodiphenylmethane (MDA)
- Diarsenic pentoxide (As₂O₅)
- Diarsenic trioxide (As₂O₃)
- Formaldehyde
- Hexabromocyclododecane (HBCDD) and all major diastereoisomers
- Hexavalent chromium compounds
- Lead and lead compounds
- Mercury and mercury compounds
- Mirex (perchlorodecane)
- Organic tin compounds (tributyl tin, tributyl tin oxide and triphenyl tin)
- Ozone-depleting substances
- Perfluorooctane sulfonates (PFOS)/Perfluorooctanoic acid (PFOA)
- Phthalates (DEHP, DBP, BBP)
- Polybrominated diphenyl ethers (PBDEs)
- Polybromobiphenyls (PBBs)
- Polychlorinated biphenyls (PCBs)
- Polychlorinated naphthalenes (PCNs)
- Polychlorinated terphenyl (PCT)
- Polyvinyl chloride (PVC) and PVC blends
- Radioactive substances
- 5-tert-butyl-2, 4,6-trinitro-m-xylene (Musk xylene)
- Tetrabromobisphenol A (TBBPA)